

Preliminary Agenda 13 August 2008

PRELIMINARY MEETING AGENDA – CE-2.2 SUBCOMMITTEE ON CONNECTOR AND SOCKET SPECIFICATIONS 6 – 7 October 2008 in SALT LAKE CITY, UT

1. Approval of the 31 March 2008 - 1 April 2008 minutes

2. SPECIFICATIONS BY PROJECT NUMBERS

"If any SP listed below receives insufficient votes for approval, the committee may approve the document for EDEC ballot at this meeting. It is the responsibility of the member to submit comments in writing prior to the meeting".

A. SP-4965, EIA-540B0AE, Detail Land Grid Array (Carl Fritz)

Sent letter (mccwil349) to EIA for SP ballot to reaffirm specification on 2 May 2008.

SP ballot issued 10 June 2008 with a ballot expiration date of 10 August 2008.

B. SP-4970, EIA-540DAAA-A, Detail, DIP

At EDEC for approval.

C. SP-4971, EIA-700A0AB, 68-pin Memory Card Connector

At EDEC for approval.

D. SP-4973: EIA-540B0AB: Low Pin Count BGA

Sent memo (mccwil347) to EIA requesting that the project and specification be cancelled on 2 May 2008 on behalf of Max Peel.

Project cancelled per Cecelia Yates at EIA on 13 May 2008. Cecelia indicated that this specification was actually issued as a letter ballot on 24 January 2002 by Tom Peel.

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E. SP-5112 as follows:

- EIA-700A0AC: Detail, 88-pin DRAM Connector
- EIA-540A000-A: Sectional, Chip Carrier Sockets
- EIA-540AA00: Blank, Leadless Chip Carrier Sockets
- EIA-540AAAA: Detail, Type A Chip Carrier Sockets
- EIA-540AB00: Blank, PQFP
- EIA-540ABAA: Detail, PQFP
- EIA-540AC00: Blank, PCC
- EIA-540ACAA: Detail, PCC
- EIA-540AD00: Blank, Adaptor QFP to PGA
- EIA-540B000: Sectional, PGA
- EIA-540BA00: Blank, PGA
- EIA-540BAAB: Detail, Non-Mechanical PGA
- EIA-540BAAC: Detail, Flex Carrier PGA
- EIA-540D000-A: Sectional, In-Line Packages
- EIA-540DA00: Blank, DIP (Will be sent out for review)
- EIA-540DAAB: Detail, Flex Carrier DIP
- EIA-540EA00: Blank, Round Sockets
- EIA-540EAAA: Detail, Round Sockets
- EIA-540F000: Sectional, Multi-Package Modules

A second letter (mccwil269) was sent to Cecelia Yates (EIA Staff) EDEC ballot on 14 August 2006.

F. PN-5123, EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets (Contech Research, Tom Peel)

Sent memo (mccwil348) to EIA requesting that the project and specification be cancelled on 2 May 2008 on behalf of Tom Peel.

3. SPECIFICATIONS AWAITING PROJECT NUMBERS

None.

4. NEW BUSINESS

Prepared by:

Carl Fritz, Facilitator, CE-2.2